SN54ABT646A ... JT OR W PACKAGE

SN74ABT646A

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DB. DW. NT. OR PW PACKAGE

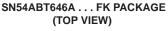
- State-of-the-Art *EPIC-*II*B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

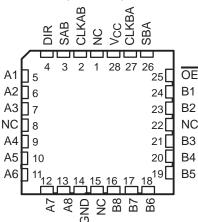
description

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646A.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

(TOP VIEW)							
CLKAB [SAB [DIR [A1 [A2 [A3 [A4 [A5 [A6 [A7 [A8 [GND [1 2 3 4 5 6 7	24 23 22 21 20 19 18 17 16 15 14 13	V _{CC} CLKBA SBA OE B1 B2 B3 B4 B5 B6 B7 B8				





NC - No internal connection

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT646A is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT646A is characterized for operation from -40° C to 85° C.



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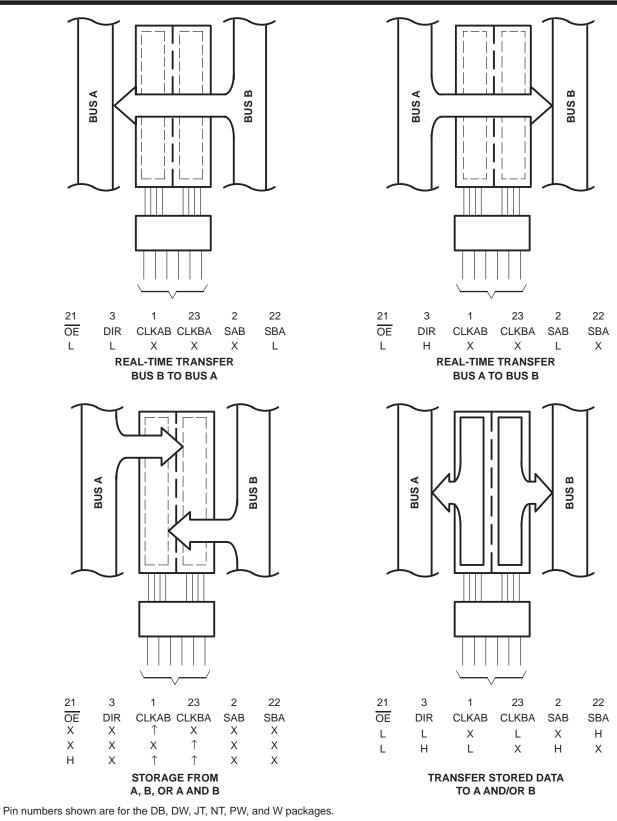


Figure 1. Bus-Management Functions

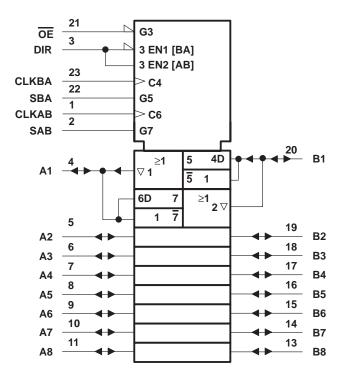


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	FUNCTION TABLE									
		INP	UTS			DATA	A I/Os	OPERATION OR FUNCTION		
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION		
Х	Х	\uparrow	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]		
х	Х	Х	\uparrow	Х	Х	Unspecified [†]	Input	Store B, A unspecified [†]		
Н	Х	\uparrow	\uparrow	Х	Х	Input	Input	Store A and B data		
Н	Х	H or L	H or L	Х	Х	Input disabled	Input disabled	Isolation, hold storage		
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus		
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus		
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus		
L	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus		

⁺ The data-output functions may be enabled or disabled by various signals at \overline{OE} and DIR. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

logic symbol[‡]

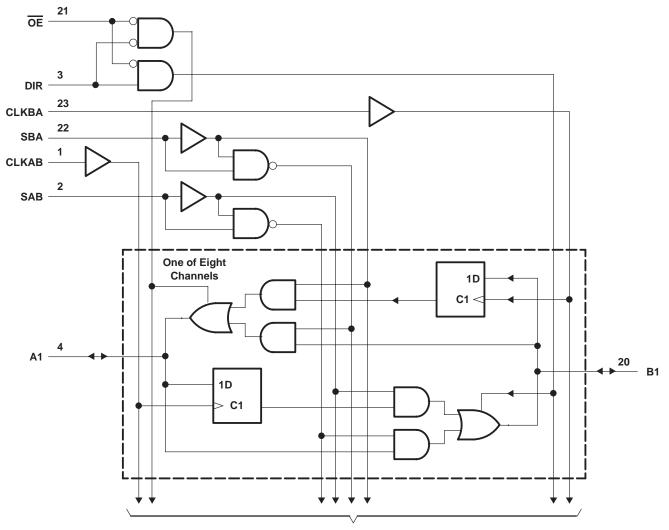


[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



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logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (except I/O ports) (see Voltage range applied to any output in the high Current into any output in the low state, I_O : SN	Note 1) or power-off state, V _O N54ABT646A	-0.5 V to 7 V -0.5 V to 5.5 V
SN	N74ABT646A	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I_{OK} ($V_O < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2)		
	DW package	
		67°C/W
	PW package	120°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT646A		SN74AB	UNIT	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
IOH	High-level output current		-24		-32	mA
IOL	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
Т _А	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54AB	T646A	SN74AB			
		TEST CO	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT		
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
Varia		$V_{CC} = 5 V,$	I _{OH} = -3 mA	3			3		3		v	
∨он		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v	
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2			
Vai		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	v	
V _{hys}					100						mV	
1.	Control inputs	$V_{CC} = 5.5 V$, $V_{I} = V_{CC}$ or GND				±1		±1		±1		
tı.	A or B ports	VCC = 5.5 V, VI =				±100		±100		±100	μA	
IOZH [‡]	ŧ	V _{CC} = 5.5 V,	$V_{O} = 2.7 V$			10§		10§		10§	μΑ	
IOZL‡		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-10§		-10§		–10§	μΑ	
loff		$V_{CC} = 0,$	VI or VO \leq 4.5 V			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
IO		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			250		250		250	μΑ	
ICC		$I_{O} = 0,$	Outputs low			30		30		30	mA	
		$V_{I} = V_{CC} \text{ or } GND$	Outputs disabled			250		250		250	μΑ	
∆ICC [#]	<i>‡</i>	$V_{CC} = 5.5 V$, One Other inputs at V_{C}				1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			7						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5	V		12						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5$ V.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ This data sheet limit may vary among suppliers.

 \P Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

					SN54ABT646A					
		V _{CC} = T _A = 2	= 5 V, 25°C	MIN	МАХ	UNIT				
			MAX							
fclock	Clock frequency	0	125	0	125	MHz				
tw	Pulse duration, CLK high or low	4		4		ns				
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns				
th	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5		ns				



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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN74AE	3T646A		
		V _{CC} = T _A = 2	= 5 V, 25°C	MIN	МАХ	UNIT
		MIN	MAX	1		
fclock	Clock frequency	0	125	0	125	MHz
tw	Pulse duration, CLK high or low	4		4		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	МАХ	UNIT
			MIN	TYP	MAX			
fmax			125			125		MHz
^t PLH	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	6.7	ns
^t PHL		AUB	1.7	4	5.1	1.2	6.7	115
^t PLH	A or B	B or A	1.5	3	4.3	1.5	5	ns
^t PHL		BOIA	1.5	3.3	4.6	1.5	5.6	115
^t PLH	0.0 00.1t	B or A	1.5	4	5.7	1.5	7.8	ns
^t PHL	SAB or SBA [†]	BOIA	1.5	3.6	4.9	1.5	6.2	115
^t PZH	OE	A or B	1.5	4.3	5.3	1.5	7	ns
^t PZL	ÛE	AUB	3	5.8	8	3	10.5	115
^t PHZ		A or B	1.5	3.5	5.8	1	7.3	
^t PLZ	OE	AOLP	1.5	3	4	1.5	5.7	ns
^t PZH	DIP	A or B	1.5	4.5	5.7	1.5	7.3	20
^t PZL	DIR	AUID	2.5	6.5	9	2.5	11	ns
^t PHZ	DIR	A or B	1.5	3.8	6.5	1	9	20
^t PLZ	אוע	AUID	1.5	3.8	4.7	1.2	6.7	ns

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



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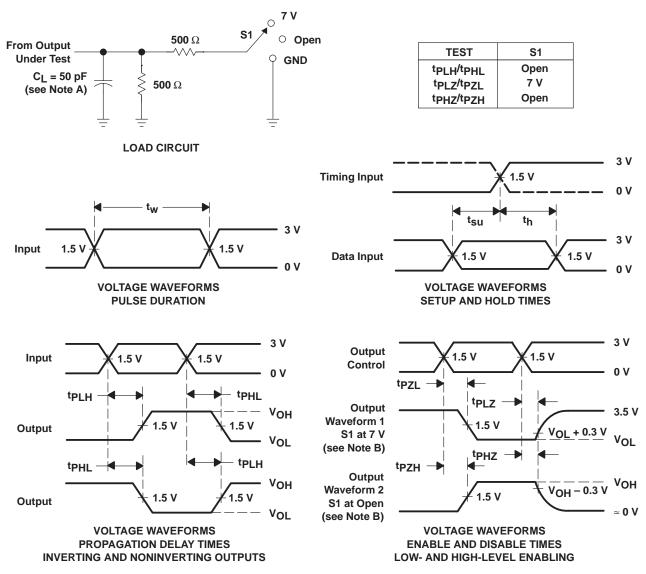
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN	МАХ	UNIT
			MIN	TYP	MAX			
fmax			125			125		MHz
^t PLH	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.6	ns
^t PHL	CLKBA OF CLKAB	AUD	1.7	4	5.1	1.7	5.6	115
^t PLH	A or B	B or A	1.5	3	4.3	1.5	4.8	ns
^t PHL		BUIA	1.5	3.3	4.6	1.5	5.4	115
^t PLH	SAB or SBA†	B or A	1.5	4	5.1	1.5	6.5	ns
^t PHL		BUIA	1.5	3.6	4.9	1.5	5.9	115
^t PZH	OE	A or B	1.5	4.3	5.3	1.5	6.3	ns
^t PZL	ÛE	AUD	3	5.8	7.4	3	8.8	115
^t PHZ	OE	A or B	1.5	3.5	4.5	1.5	5	ns
^t PLZ	ÛE	AOID	1.5	3	4	1.5	4.5	115
^t PZH	PIP	A or B	1.5	4.5	5.7	1.5	6.7	
t _{PZL}	DIR	AUID	2.5	6.5	9	2.5	9.5	ns
^t PHZ	DIR	A or B	1.5	3.8	5	1.5	5.7	
^t PLZ	DIR	AUIB	1.5	3.8	4.7	1.5	6	ns

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



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